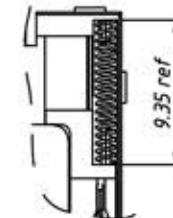
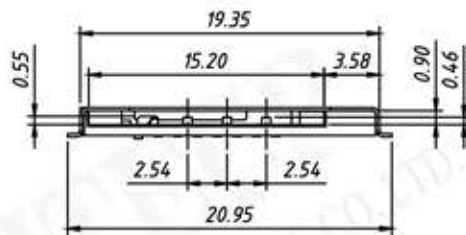
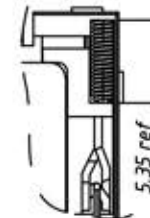


Pin No.	DESCRIPTION
P1#	C1-VCC
P2#	C5-GND
P3#	C2-RST
P4#	C6-VPP
P5#	C3-CLK
P6#	C7-I/O
P7#	POL
P8#	DET

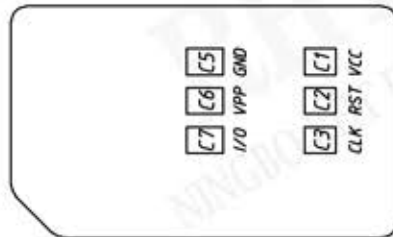


Preloading state



Working condition

SOLDER AREA  
 NONE CIRCUIT DIAGRAM AREA



SIM diagram  
Chip face down view

**Material:**

Insulator: High Temperature Thermoplastic

Contact: Copper Alloy

Shell: Steel

Finish:

Contact: Gold Flash Plated on Contact Area;

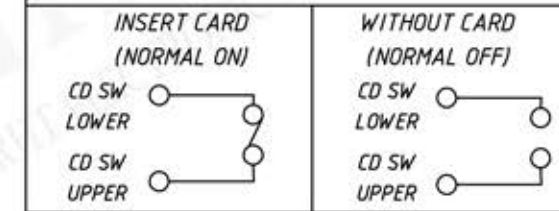
Matte-Tin Plated on Solder Tails;

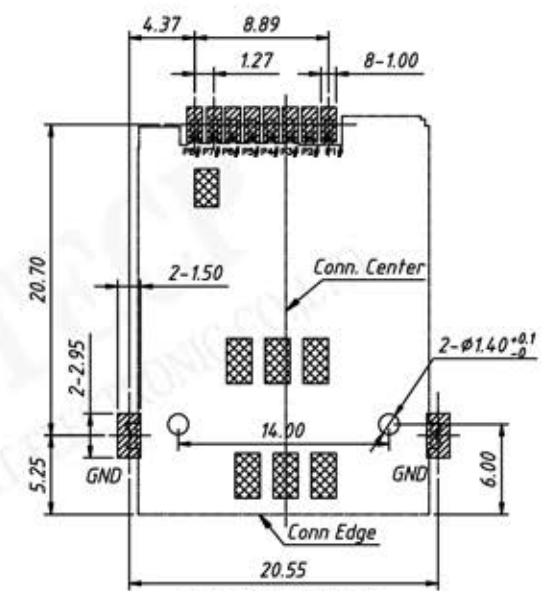
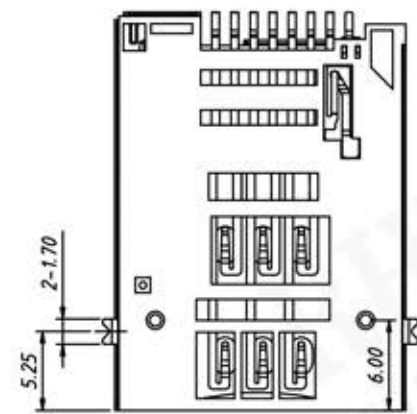
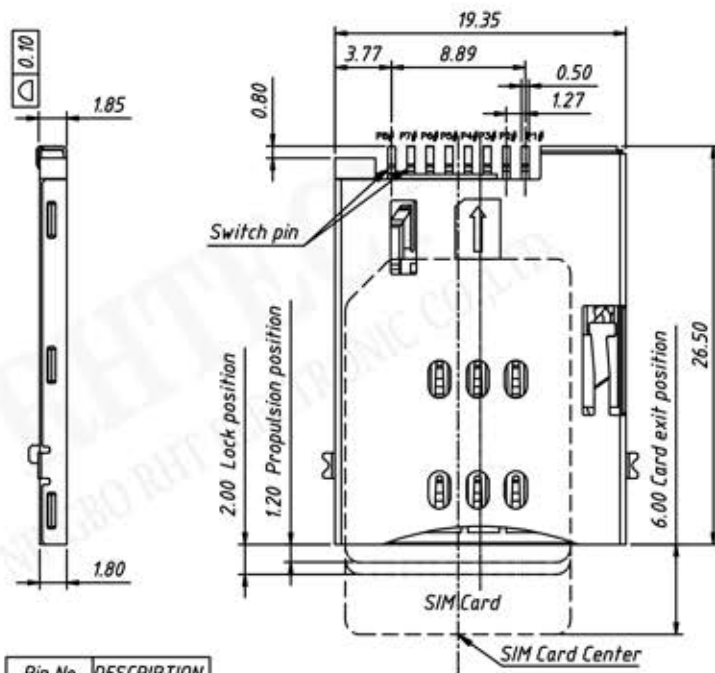
With Entire Contact Underplated Nickel.

Shell: Gold Flash Plated on Solder Tails.

Infrared Reflow Soldering: 10 sec. Min. at 260<sup>±10</sup>

**Circuit Diagram for Card Detect Switch**

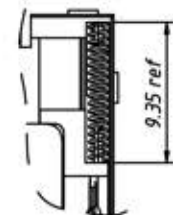
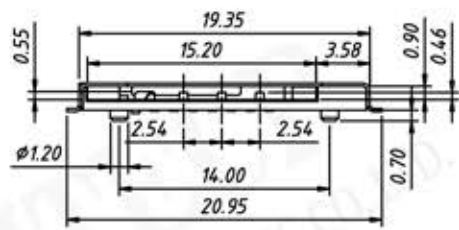




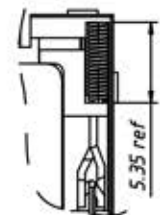
RECOMMENDED PCB LAYOUT  
GENERAL TOLERANCE ±0.05

▨ SOLDER AREA  
▩ NONE CIRCUIT DIAGRAM AREA

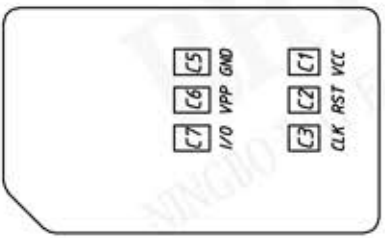
Pin No.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



Preloading state



Working condition



SIM diagram  
Chip face down view

Material:  
Insulator: High Temperature Thermoplastic  
Contact: Copper Alloy  
Shell: Steel  
Finish:  
Contact: Gold Flash Plated on Contact Area;  
Matte-Tin Plated on Solder Tails;  
With Entire Contact Underplated Nickel.  
Shell: Gold Flash Plated on Solder Tails.  
Infrared Reflow Soldering: 10 sec. Min. at 260<sup>±10</sup>

